Initial Product/Process Change Notification

Document #:IPCN25369Z1
Issue Date:03 Apr 2024

Title of Change:	Cancelation of **IPCN25369Z** - To inform customers that defined changes in the original IPCN (Wafer Fabrication transfer from onsemi Bucheon, Korea to onsemi Aizu, Japan for HDG family of gate drivers. Wafer Probe location change from Bucheon, Korea to Greatek Electronics Inc (GTK) will no longer take effect.
Proposed Changed Material First Ship Date:	N/A
Current Material Last Order Date:	N/A *Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability*.
Current Material Last Delivery Date:	N/A *The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.*
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local onsemi Sales Office or John.Butchko@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.

Change Category

Category	**Type of Change**
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter

Description and Purpose:

This IPCN wants to notify customers regarding the **cancelation** of **IPCN25369Z**.

Reason / Motivation for Change:	Cancellation of a Previous PCN
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Aizu, Japan	Greatek Electronics Inc., Taiwan

Marking of Parts/ Traceability of Change:	Part marking shows assembly site and assembly date, only. Assembly lot (marked on reel and shipping boxes) is traceable to source wafer fab.

Qualification Plan:

N/A

Electrical Characteristics Summary:

N/A

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Current Part Number	New Part Number	Qualification Vehicle
FAN7083MX-GF085	FAN7083MX-GF085	FAN7191MX-F085
FAN7085MX-GF085	FAN7085MX-GF085	FAN7191MX-F085
FAN7171MX-F085	FAN7171MX-F085	FAN7191MX-F085
FAN7191MX-F085	FAN7191MX-F085	FAN7191MX-F085
FAD7171MX	FAD7171MX	FAD6263M1X
FAD8253MX-1	FAD8253MX-1	FAD8253MX-1
FAN7081MX-GF085	FAN7081MX-GF085	FAN7191MX-F085
FAN7080MX-GF085	FAN7080MX-GF085	FAN7191MX-F085
FAD8253MX	FAD8253MX-1	FAD8253MX-1
FAD7191M1X	FAD7191M1X	FAD6263M1X
FAD6263M1X	FAD6263M1X	FAD6263M1X